

<b>Form PTO-1449</b>  <b>LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	<b>ATTORNEY DOCKET NO.</b> 70030260-1	<b>SERIAL NO.</b> 10/608,606
	<b>APPLICANT</b> Lee et al.	
	<b>FILING DATE</b> June 27, 2003	<b>GROUP</b> 2249

REFERENCE DESIGNATION		U.S. PATENT DOCUMENTS		
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME
SC		5,640,048	June 17, 1997	Selna
		5,986,885	November 16, 1999	Wyland
		6,084,295	July 4, 2000	Horiuchi et al.
		6,191,477	February 20, 2001	Hashemi
		6,268,654	July 31, 2001	Glenn et al.
SC		6,620,720	September 16, 2003	Moyer et al.

FOREIGN PATENT DOCUMENT					
		DOCUMENT NUMBER	DATE	NAME	TRANSLATION YES NO

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)		
SC		Syd R. Wilson, Clarence J. Tracy, and John L. Freeman, Jr., "Handbook of Multilevel Metallization for Integrated Circuits", Noyes Publ., Westwood, New Jersey (1993), pp. 868 - 872.
SC		Electronic Packaging and Production, "Innovative PCB Reinforcement", (February, 1997), p. 1.
SC		Johannes Adam, "New Correlations Between Electrical Current and Temperature Rise in PCB Traces", Proc. 20th IEEE Semi-Therm Symp., (March 2004), pp. 1 - 8.
<b>EXAMINER</b> /Sara Crane/ <b>DATE CONSIDERED</b> 01/04/2007		

\* Copies of these references are not enclosed Pursuant to 37 CFR 1.98(d). (See accompanying IDS)

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